

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jung Bae Jun	04/24/2007
Jin Gyu Park	04/25/2007
Heung Se Lee	04/25/2007
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Cheil Industries, Inc.
<b>Street Address:</b>	290, Kongdan-Dong
<b>City:</b>	Kumi-Shi
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	730030
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11500018
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NAME OF SUBMITTER:	Candi L. Riggs

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Total Attachments: 2  
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**ASSIGNMENT**

THIS ASSIGNMENT, made by us, **Jung Bae Jun**, a citizen of the Republic of Korea, residing at e-Pyeonhansesang 115-1501, Yonghomaeul, Dang-dong, Kunpo-si, Kyeonggi-do, Republic of Korea; **Jin Gyu Park**, a citizen of the Republic of Korea, residing at Jukong Apt. 301-1201, 688 Deungchon-dong, Kangseo-ku, Seoul-si, Republic of Korea; and **Heung Se Lee**, a citizen of the Republic of Korea, residing at Room #202, 795-2 Bono 2-dong, Sangrok-Ku, Ansan-si, Kyeonggi-do, Republic of Korea;

WITNESSETH: That,

WHEREAS, we are joint inventors of certain new and useful improvements in **CONDUCTIVE PARTICLES FOR ANISOTROPIC CONDUCTIVE INTERCONNECTION** for which U.S. Application No. 11/500,018 was filed on August 7, 2006, in the United States Patent and Trademark Office; and

WHEREAS, **Cheil Industries, Inc.**, a Korean corporation having a principal place of business at 290, Kongdan-Dong, Kumi-Shi 730-030, Republic of Korea, hereinafter referred to as assignees, are desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer, and convey unto the said assignee, its successors and assigns, the entire right, title, and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues or other forms of protection thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted along with any term extensions thereon or therefor, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

**ASSIGNMENT - CONTINUED**

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to promptly communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors, or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignees, its successors, assigns, and other legal representatives; and we hereby instruct, and further covenant and agree to bind our heirs, legal representatives, and assigns, to do same, without further compensation, but at the expense of said assignee or its representatives.

IN WITNESS WHEREOF, we have hereunto set our hands and seals on this 25 day of April, 2007.

Jung Bae Jun (SEAL)  
**Jung Bae Jun**

[Signature] (SEAL)  
**Jin Gyu Park**

Miw (SEAL)  
**Heung Se Lee**

Witnessed by: \_\_\_\_\_

Witnessed by: \_\_\_\_\_

Date: \_\_\_\_\_

Date: \_\_\_\_\_